Product Change Notification

Change Notification #:	**118874-00**
Change Title:	**Intel® Server Board D40AMP1SB, Intel® Compute Module D40AMP1MHCPAC, Intel® Server Chassis VP3U2HAC21W0, Intel® Server Chassis VP3000 U.2 Hot Swap Backplane Assembly VP3U2HSBASSMBLF, PCN 118874-00, Product Design, Firmware Update**
Date of Publication:	**January 21, 2022**

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material*	February 05, 2022

* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the products listed in the Products Affected table below:

1. The firmware on the server board will be updated:
   - BIOS from version R01.02.0002 to version R01.02.0006
   - BMC from version 2.87.5fef98fb to version 2.87.3ccd0377
   - FRU/SDR data from version 0.19 to version 0.20
   - CPLD code from version v1p6 to version v1p7

2. The firmware on the hot swap backplane for VP3000 chassis supporting U.2 SSDs will be updated from version v0p9 to version v1p1.

Customer Impact of Change and Recommended Action:

Intel encourages customers to understand the change and determine the impact on their applications. For that reason, Intel recommends that the customer perform a standard level of evaluation.

This firmware components mentioned above are contained in the System Update Package (SUP) and System Firmware Update Package (SFUP) that are available for download from http://www.intel.com/support.

Please refer to the release notes included into the SUP and SFUP for the list of changes.

Products Affected/Intel Ordering Codes:

Marketing Name	**Product Code**	**MM#**	**Pre Change TA**	**Pre Change PBA**	**Post Change TA**	**Post Change PBA**
Intel® Server Board D40AMP1SB, Single	D40AMP1SB	99AH9K	M48842-250	M21913-250	M48842-251	M21913-251
Intel Server System D40AMP1MHCPAC Compute Module (1U Half-Width Air-Cooled), Single	D40AMP1MHCPAC	99AH9L	M40302-001		M40302-002	
U.2 Hot Swap Backplane Assembly Front VP3U2HSBASSMBLF, Single	VP3U2HSBASSMBLF	99AJLJ	M42267-001	M26071-150	M42267-002	M26071-151
Intel® Server Chassis VP3U2HAC21W0 (Half-Width Configuration for U.2 Air-Cooled), Single	VP3U2HAC21W0	99AJLT	M40314-001		M40314-002	

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
January 21, 2022	00	Originally Published PCN

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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